

TRANSMITTAL FORM

Receipt
Attorney Docket No.

P3P2000078US/2369NP

COPY OF PAPERS
ORIGINALLY FILED

In re the application of OKUDA, et al.

Serial No: 10/018,708

Filed: Dec 13, 2001

Date: August 19, 2002

Group Art Unit: 3723

Examiner: unknown

For: Table of Wafer Polishing Apparatus, Method for Polishing Semiconductor Wafer, and Method for Manufacturing Semiconductor Wafer

ENCLOSURES (check all that apply)

<input type="checkbox"/>	Amendment/Reply	<input type="checkbox"/>	Assignment and Recordation Cover Sheet	<input type="checkbox"/>	After Allowance Communication to Group		
<input type="checkbox"/>	After Final	<input type="checkbox"/>	Part B-Issue Fee Transmittal	<input type="checkbox"/>	Appeal Communication to Board of Appeals and Interferences		
<input type="checkbox"/>	Information disclosure statement	<input type="checkbox"/>	Letter to Draftsman	<input type="checkbox"/>	Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)		
<input type="checkbox"/>	Form 1449	<input type="checkbox"/>	Drawings	<input type="checkbox"/>	Status Letter		
<input type="checkbox"/>	(X) Copies of References	<input type="checkbox"/>	Petition	<input checked="" type="checkbox"/>	Postcard		
<input type="checkbox"/>	Extension of Time Request *	<input type="checkbox"/>	Fee Address Indication Form	<input checked="" type="checkbox"/>	Other Enclosure(s) (please identify below):		
<input type="checkbox"/>	Express Abandonment	<input type="checkbox"/>	Terminal Disclaimer	Request for Corrected Filing Receipt			
<input type="checkbox"/>	Certified Copy of Priority Doc	<input type="checkbox"/>	Power of Attorney and Revocation of Prior Powers				
<input type="checkbox"/>	Response to Incomplete Appln	<input type="checkbox"/>	Change of Correspondence Address				
<input type="checkbox"/>	Response to Missing Parts	*Extension of Term: Pursuant to 37 CFR 1.136, Applicant petitions the Commissioner to extend the time for response for xxxxxx month(s), from to .					
<input type="checkbox"/>	Executed Declaration by Inventor(s)						

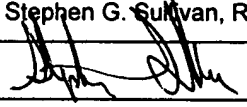
CLAIMS

FOR	Claims Remaining After Amendment	Highest # of Claims Previously Paid For	Extra Claims	RATE	FEE
Total Claims	0	0	0	\$18.00	\$ 0.00
Independent Claims	0	0	0	\$84.00	\$ 0.00
Total Fees					\$ 0.00

METHOD OF PAYMENT

<input type="checkbox"/>	Check no. _____ in the amount of \$ _____ is enclosed for payment of fees.
<input type="checkbox"/>	Charge \$ _____ to Deposit Account No. _____ (Account Holder Name) for payment of fees.
<input checked="" type="checkbox"/>	Charge any additional fees or credit any overpayment to Deposit Account No. <u>02-2120</u> (Sawyer Law Group LLP).

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

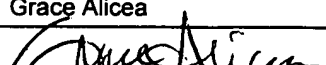
Attorney Name	Stephen G. Sullivan, Reg. No. 38,329
Signature	
Date	August 19, 2002

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Grade A/eta

COPY OF PAPERS
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Date: August 19, 2002

OKUDA, et al.

Serial No. 10/018,708

Group Art Unit: 3723

Filed: April 15, 2002

Examiner: to be assigned

For: **TABLE OF WAFER POLISHING APPARATUS, METHOD FOR POLISHING SEMICONDUCTOR WAFER, AND METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER**

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Assistant Commissioner for Patents
Washington, D.C. 20231

TECHNOLOGY CENTER R3700

REQUEST FOR CORRECTED FILING RECEIPT

Sir:

Attached is a copy of the official filing receipt received from the PTO in the above application for which issuance of a corrected filing receipt is respectfully requested.

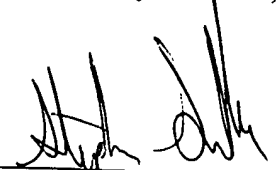
There is an error with regard to the title of the invention. The title is incorrectly recorded as ... **Table of wafer polisher, method of polishing wafer, and method of manufacturing semiconductor wafer.** The correct title is ... **Table of Wafer Polishing Apparatus, Method for Polishing Semiconductor Wafer, and Method for Manufacturing Semiconductor Wafer.** This title should be corrected.

The correction is not due to any error by applicant and no fee is due.

If any unresolved issues remain, please contact Applicant's attorney at the telephone number indicated below. If any unresolved issues remain, please contact Applicant's attorney at the telephone number indicated below.

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Respectfully submitted,


Stephen G. Sullivan
Sawyer Law Group LLP
Attorney for Applicants
Reg. No. 38,329



JUN 04 2002

UNITED STATES PATENT AND TRADEMARK OFFICE

JAS ONDA 2369NP

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/018,708	04/15/2002	3723	2218	P3p2000078US/2369NP	11	37	6

Sawyer Law Group
PO Box 51418
Palo Alto, CA 94303

CONFIRMATION NO. 1643

FILING RECEIPT



OC00000008182994

Date Mailed: 05/29/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/03899 06/15/2000

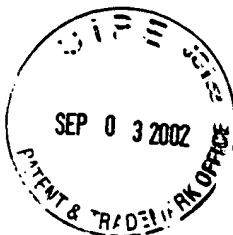
Foreign Applications

JAPAN 11/168522 06/15/1999
JAPAN 11/168523 06/15/1999
JAPAN 11/185333 06/30/1999
JAPAN 11-237507 08/24/1999
JAPAN 11-237508 08/24/1999
JAPAN 11-237509 08/24/1999
JAPAN 11-239900 08/26/1999
JAPAN 11-277117 09/29/1999
JAPAN 11-277118 09/29/1999RECEIVED
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Projected Publication Date: Not Applicable, filed prior to November 29, 2000

Non-Publication Request: No

Early Publication Request: No



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Title

Table of wafer polisher, method of polishing wafer, and method of manufacturing semiconductor wafer

Preliminary Class

451

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Title 37, Code of Federal Regulations, 5.11 & 5.15**

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NOT GRANTED

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